

520.216
Introduction to VLSI Systems
Lecture 3

Integrated Circuits Fabrication
and
Very Large Scale Integration

Charges and Their Movement (I)

- Electrons
- Ions

Where?

Solids
Liquids
Gases

and

How Well?

Superconductors
Conductors
Semiconductors
Insulators

INTERFACES

How?

Drift / Diffusion (Classical)
Tunneling (Quantum Mechanical)

Charges and Their Movement (II)

FUNCTIONAL

- Electrical conduits (1D, 2D, 3D)
- Transistors
- Switches

STRUCTURAL

- Etching
- Film deposition (electroplating)

REDOX

We now consider transport in the solid-state and more specifically in the semiconductor Silicon

the microelectronics world does not use SI units! distance will be measured in **cm** and not meters.

for example: conductivity has units of ohm-cm

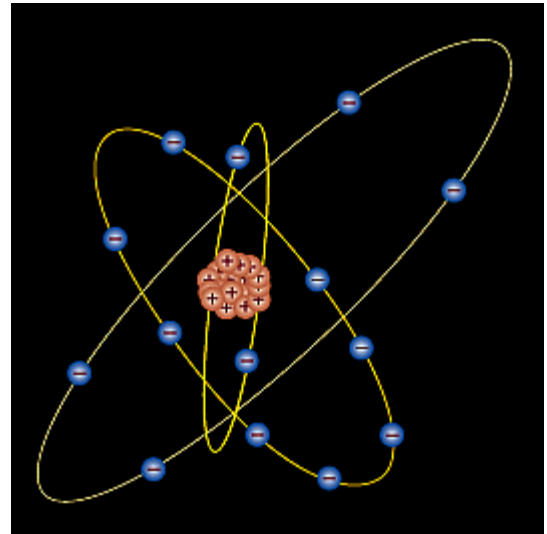
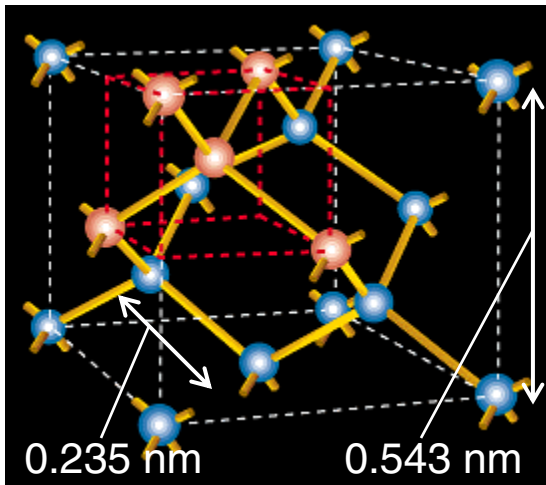
Silicon!

14

Si Silicon

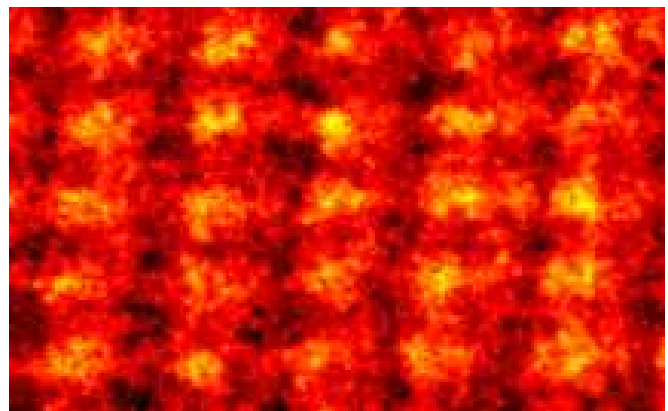
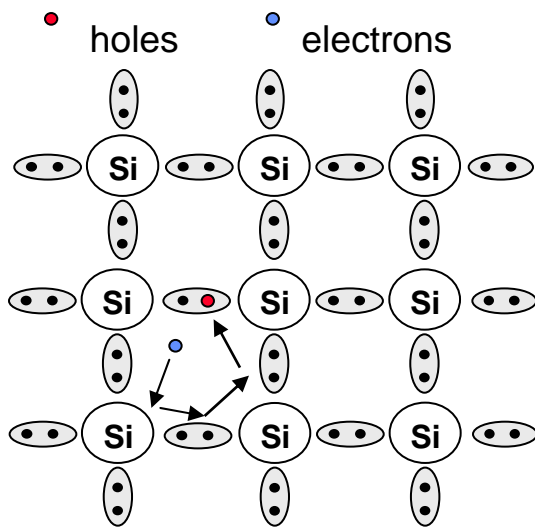
6	C
14	Si
32	Ge
50	Sn
82	Pb
114	Uuq

semiconductor



14 electrons
4 valence electrons

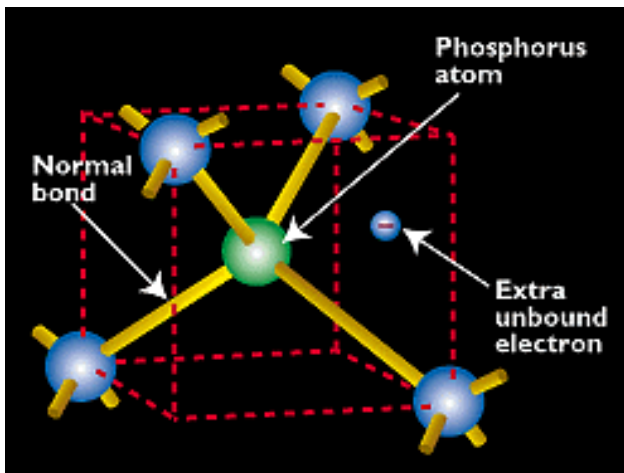
Silicon molecule
5 silicon atoms in a unit cell
Diamond lattice
Covalent bonds



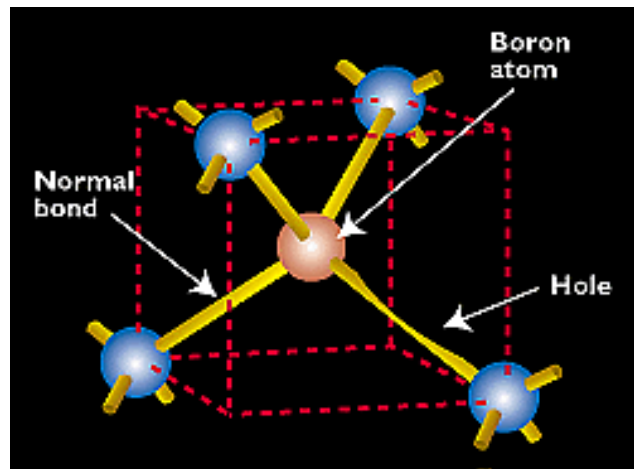
P.D. Neillist, "Incoherent Transmission Electron Microscopy"
Phys. Rev. Lett. 81, 4156 (9 Nov. 1998)

Silicon molecules: <http://www.eere.energy.gov/pv/simolecule.html>

Doped Silicon



N- doped

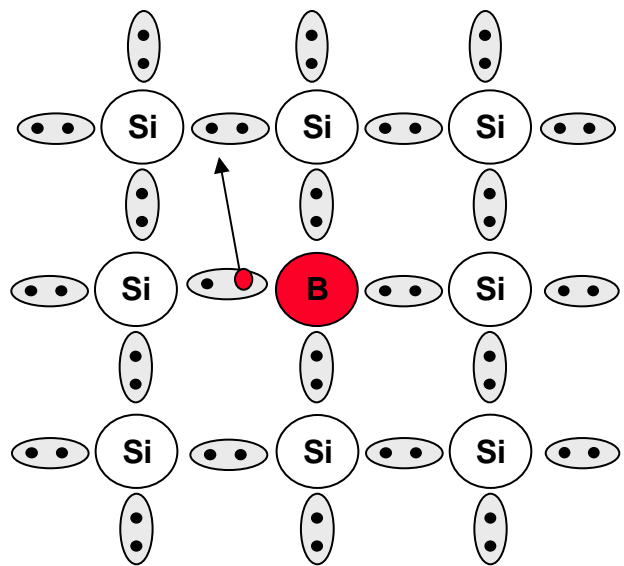
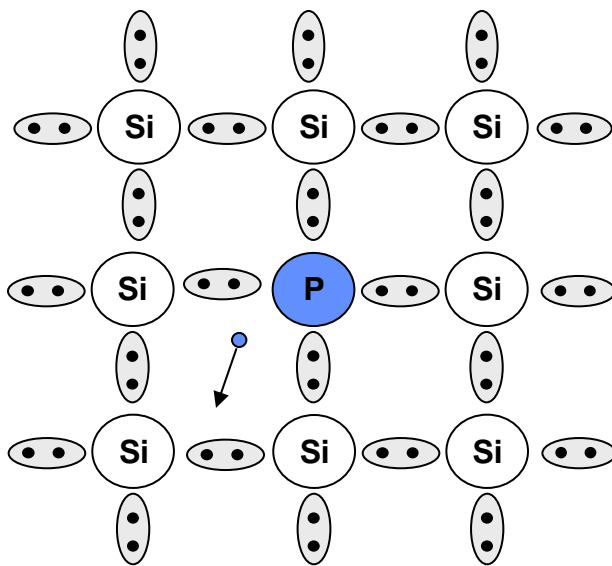


P- doped

- bound electrons

- free electrons

and ● holes



Silicon molecules: <http://www.eere.energy.gov/pv/simolecule.html>

Equilibrium Carrier Densities

$$n_n p_o = n_i^2 = 10^{20} \text{ cm}^{-3}$$

where n_o is electron and p_o hole carrier concentrations

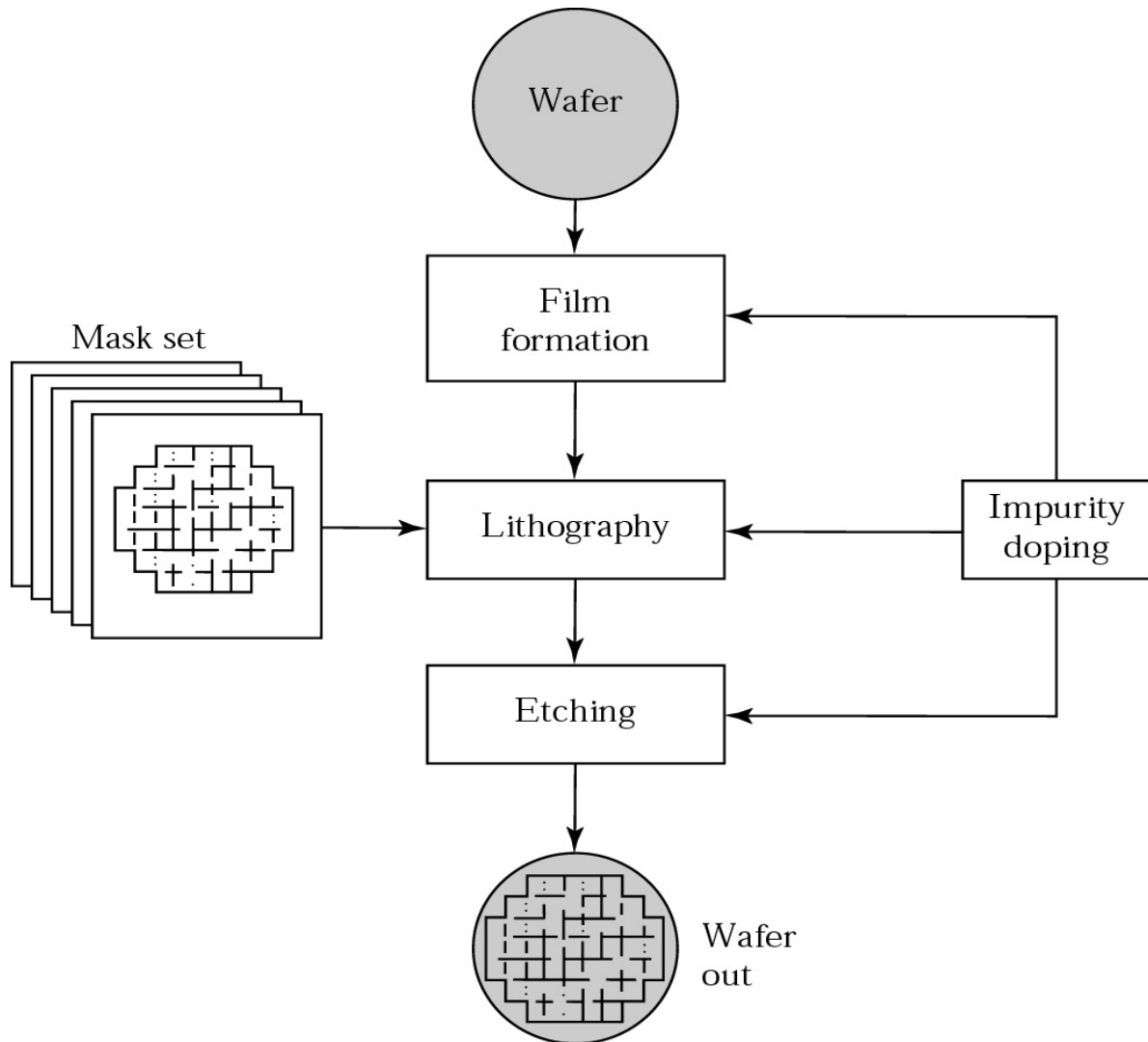
in most cases of interest the donor doping N_D or acceptor N_A doping concentration is much larger than the intrinsic concentration n_i so that

$$p_o = N_A \quad \text{and} \quad n_o = \frac{n_i^2}{N_A} \quad p\text{-type}$$

$$n_o = N_D \quad \text{and} \quad p_o = \frac{n_i^2}{N_D} \quad n\text{-type}$$

by convention, donor or acceptor concentrations as well as electron and hole concentrations are given as a number per cm^3

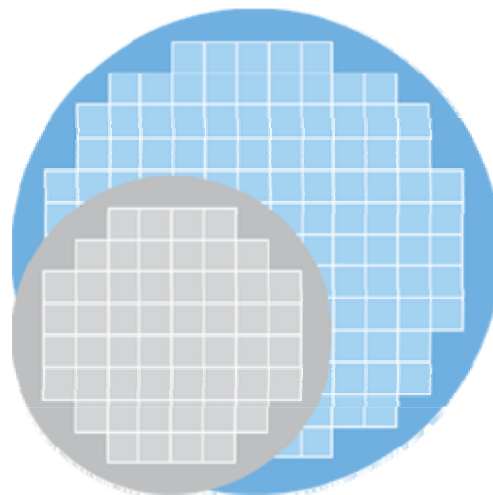
Integrated Circuit Fabrication



Where is it done?



UMC 300mm wafers

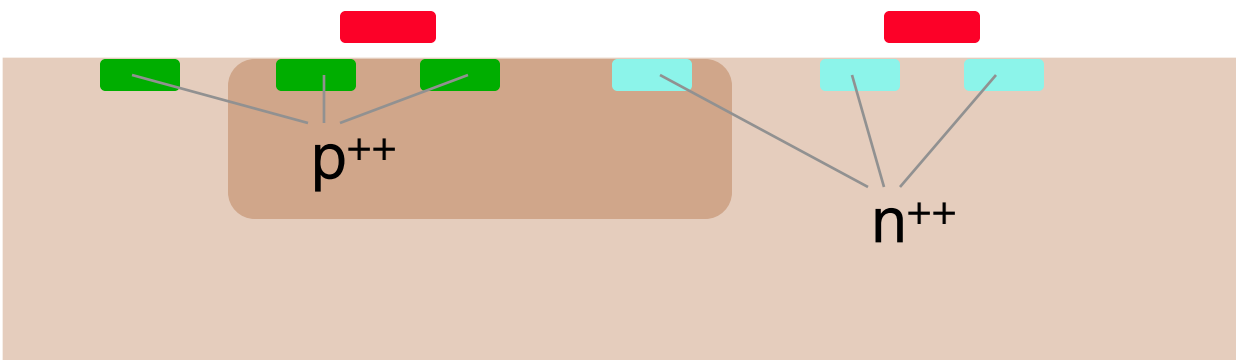
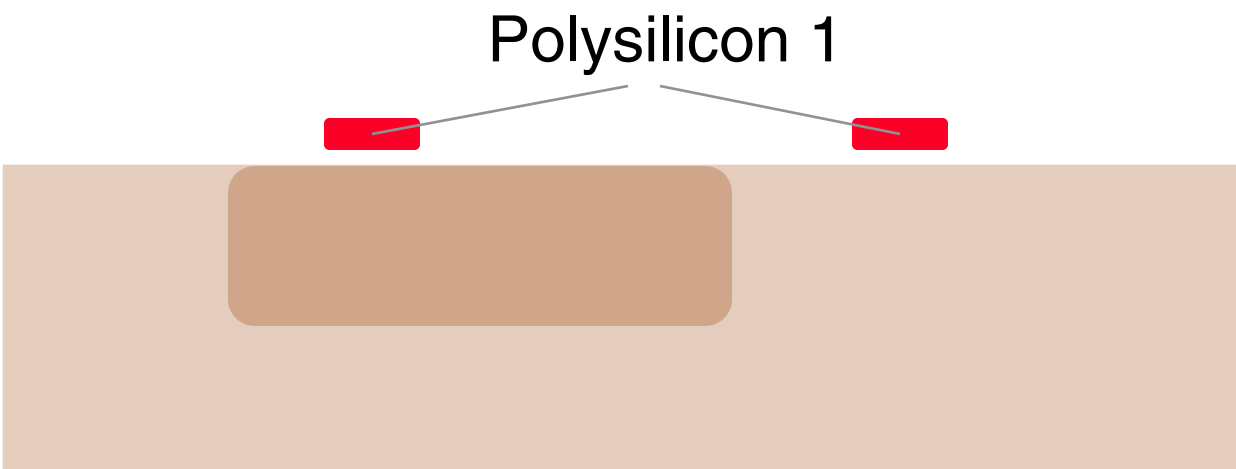


Die size: 20x20 mm²
300mm ODFW: 148
200mm ODFW: 67 - **2.6**

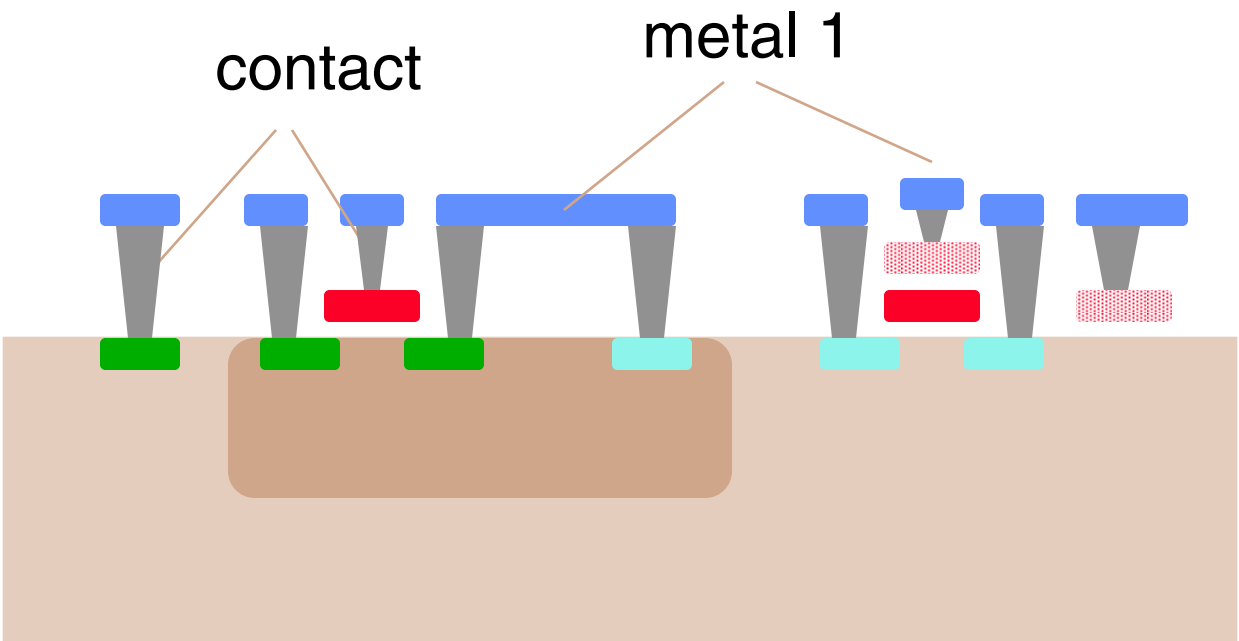
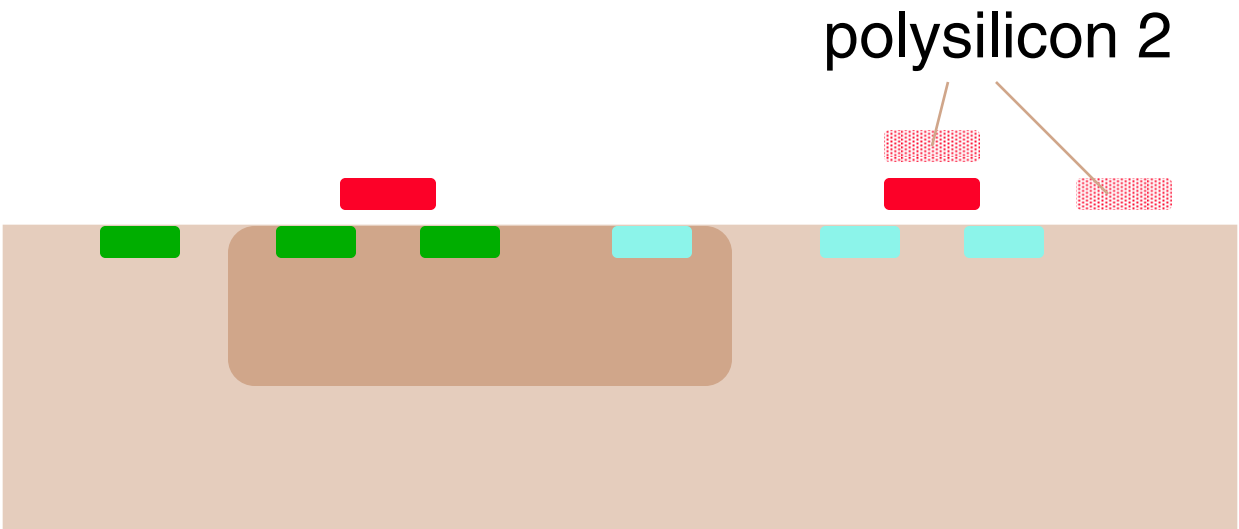
Basic CMOS components

- Conductors
- Switches (MOS transistors)
- Capacitors (MOS capacitors)
- Inductors
- Resistors

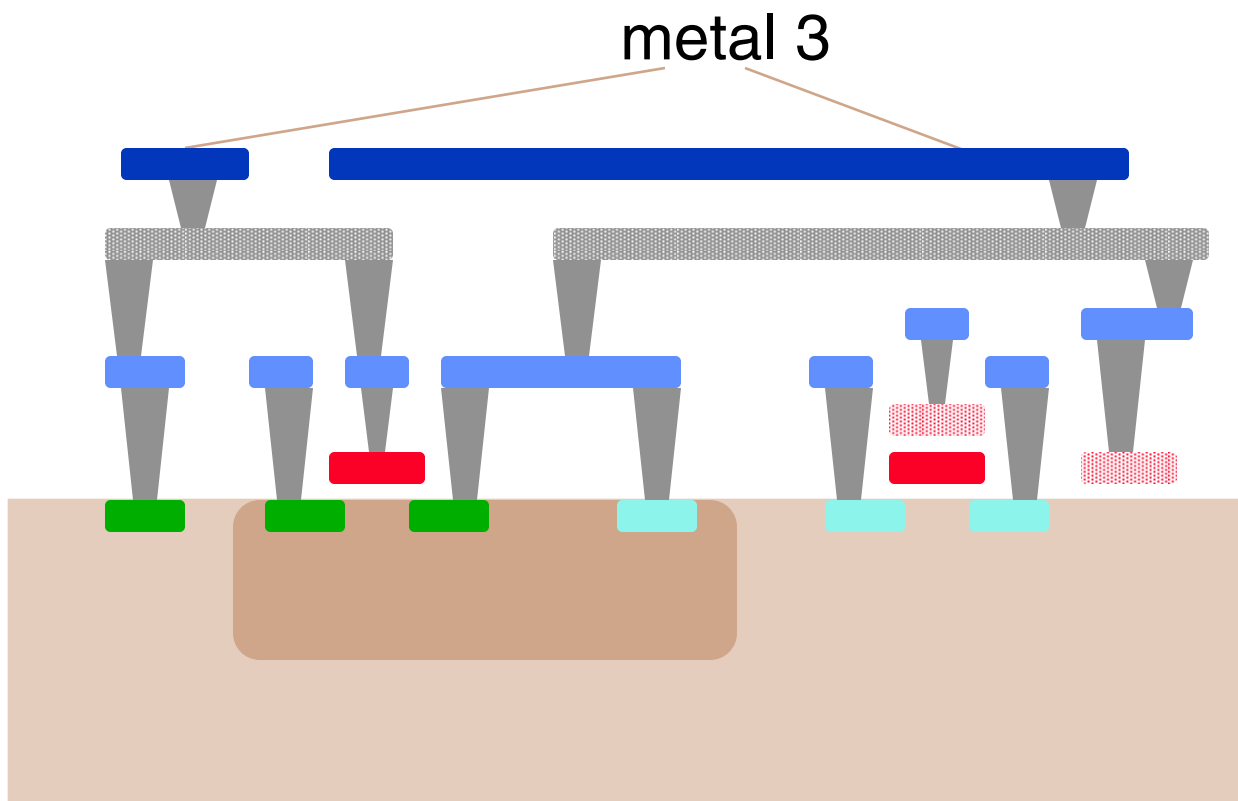
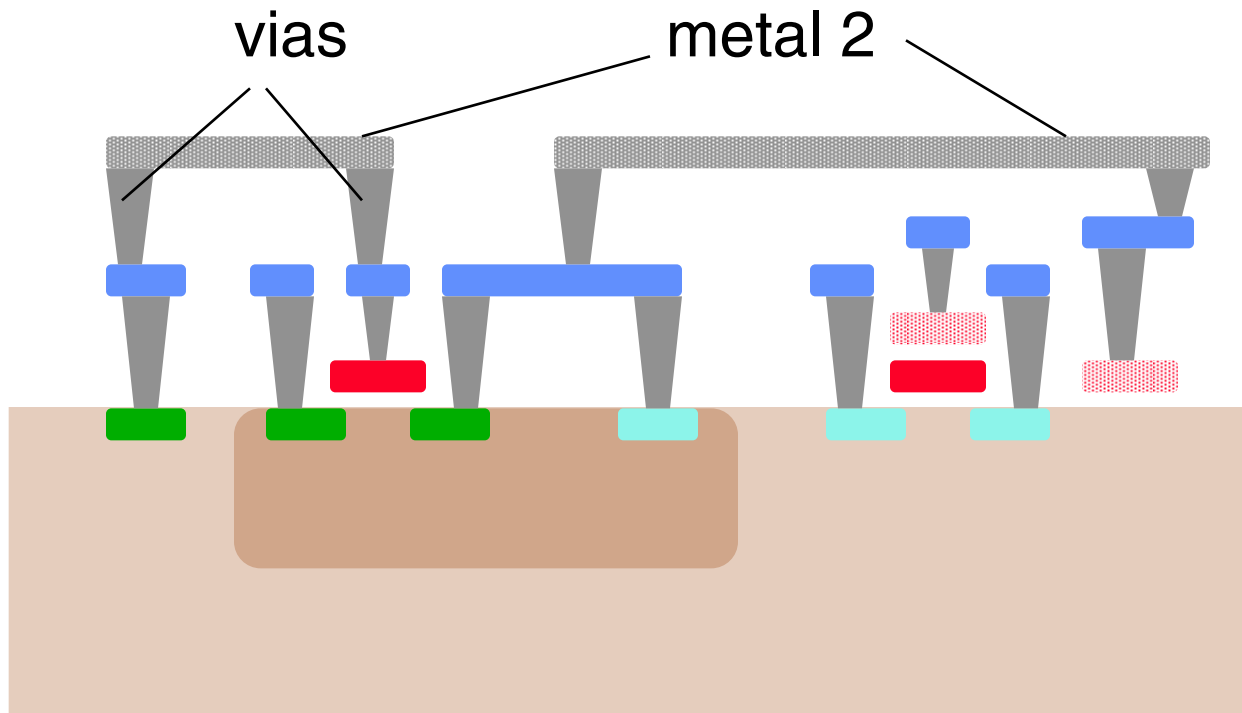
Bulk CMOS Technology (I)



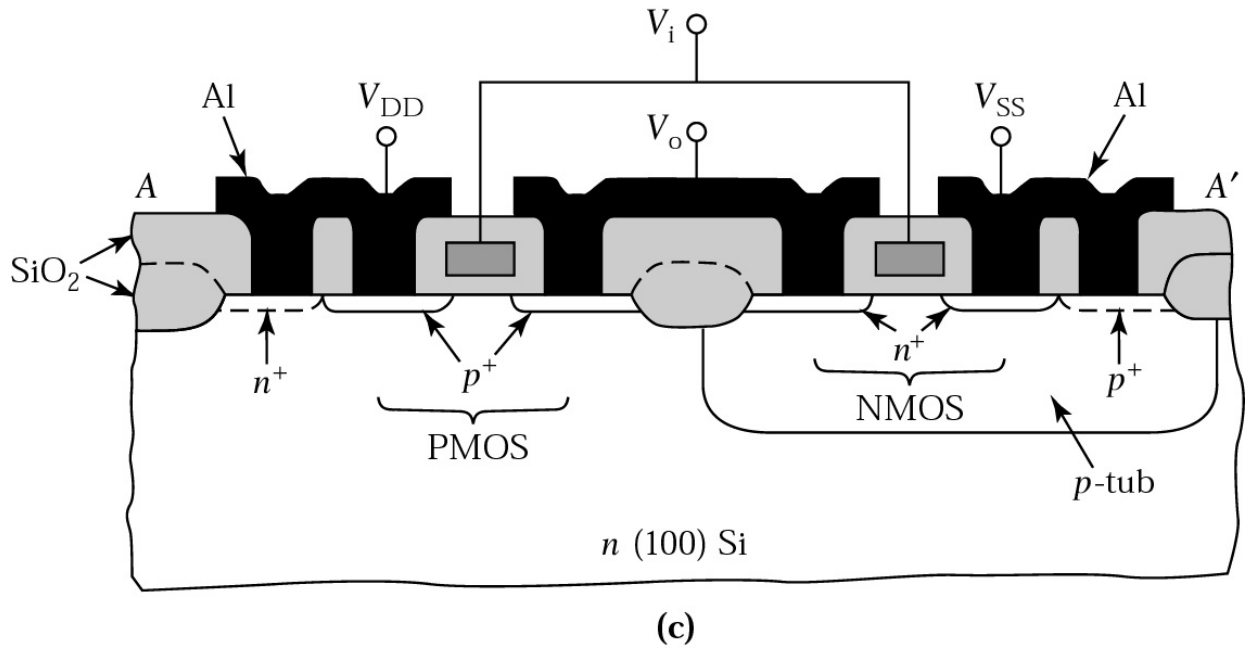
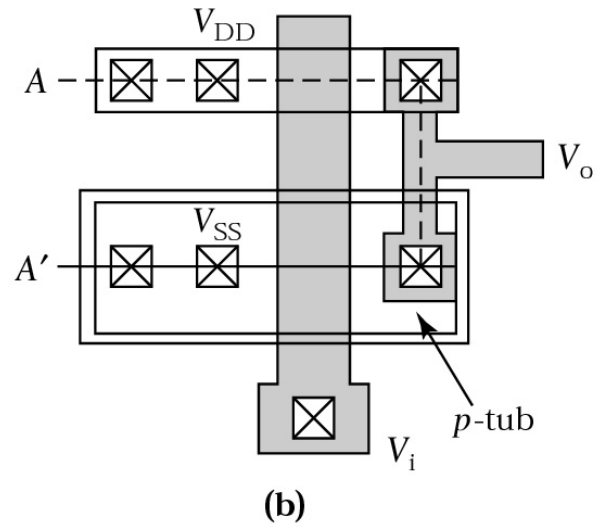
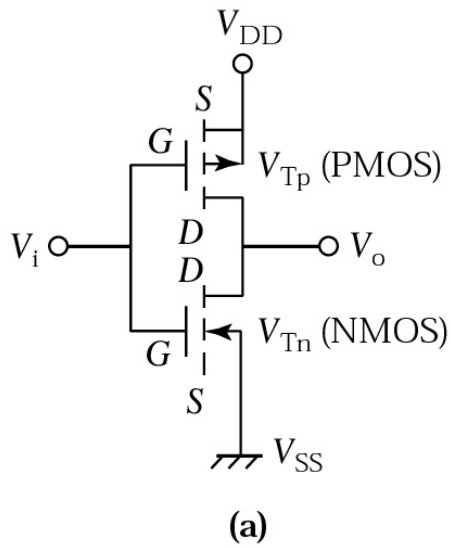
Bulk CMOS Technology (II)



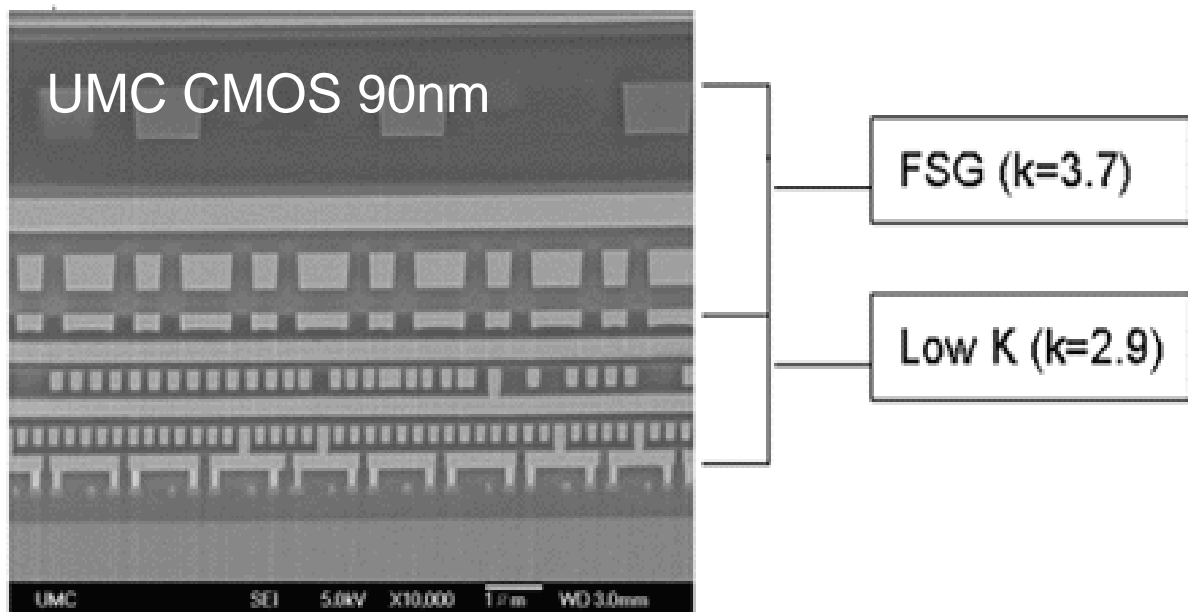
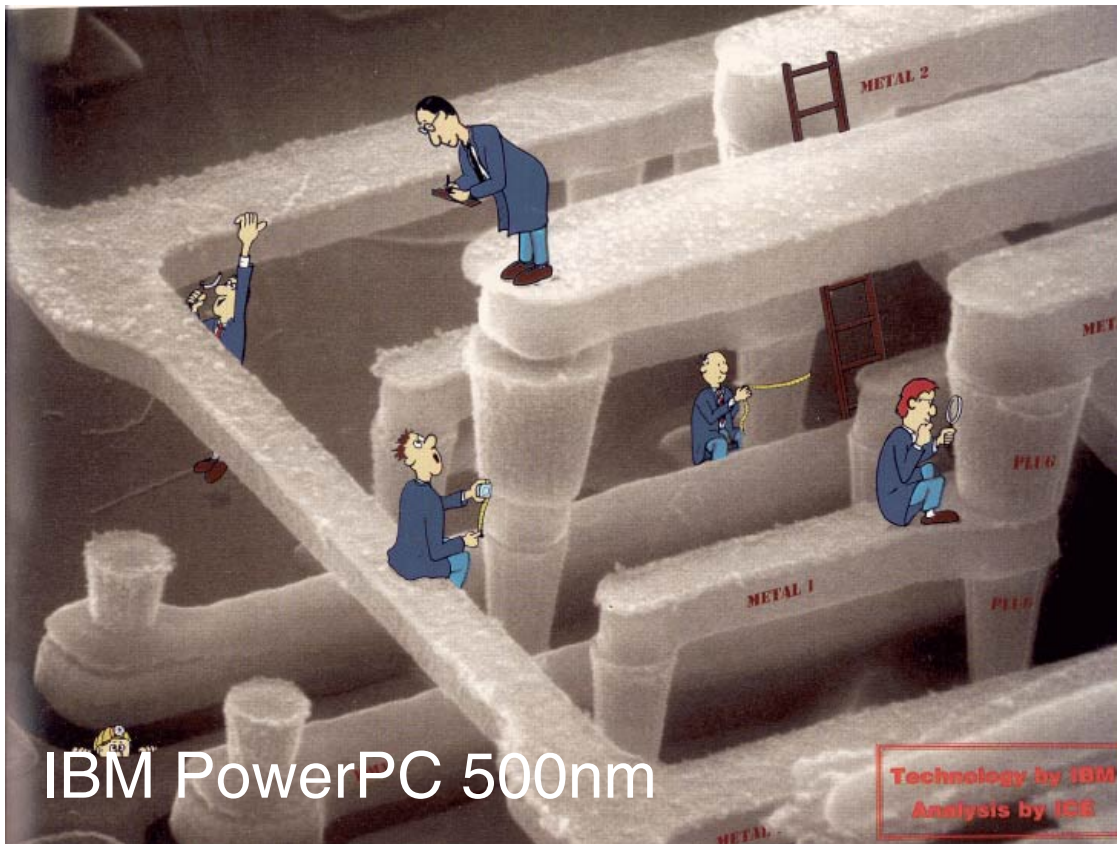
Bulk CMOS Technology (III)



CMOS Inverter



Metallization Details



L90 1P9M Cu/Low-k ($k < 2.9$)